6-103166-8 ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 6-103166-8

PCB Mount Header, Right Angle, Wire-to-Board / Board-to-Board,

40 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold,

AMPMODU Headers

View on TE.com >



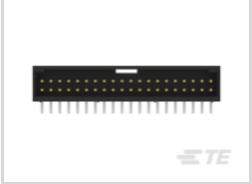
Connectors > PCB Connectors > PCB Headers & Receptacles











PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Right Angle

Connector System: Board-to-Board, Wire-to-Board

Number of Positions: 40
Number of Rows: 2

Features

Product Type Features

| PCB Connector Assembly Type | PCB Mount Header |
|-----------------------------------|-------------------------------|
| Connector System | Board-to-Board, Wire-to-Board |
| Header Type | Fully Shrouded |
| Connector & Contact Terminates To | Printed Circuit Board |
| Configuration Features | |
| Connector Contact Load Condition | Fully Loaded |
| | |
| PCB Mount Orientation | Right Angle |

Electrical Characteristics

Number of Rows

| Insulation Resistance | 5000 ΜΩ |
|---------------------------------------|----------|
| Dielectric Withstanding Voltage (Max) | 750 Vrms |

2

Body Features

| Connector Profile | Standard | |
|-------------------|----------|--|



| Primary Product Color | Black |
|---|-------------------------------|
| Contact Features | |
| Mating Square Post Dimension | .64 mm[.025 in] |
| PCB Contact Termination Area Plating Material Thickness | 2.54 – 5.08 μm[100 – 200 μin] |
| Contact Shape & Form | Square |
| Contact Underplating Material | Nickel |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Base Material | Phosphor Bronze |
| Contact Mating Area Plating Material | Gold |
| Contact Mating Area Plating Material Thickness | .762 μm[30 μin] |
| Contact Type | Pin |
| Contact Current Rating (Max) | 3 A |
| Termination Features | |
| Square Termination Post & Tail Dimension | .64 mm[.025 in] |
| Termination Post & Tail Length | 3.43 mm[.135 in] |
| Termination Method to Printed Circuit Board | Through Hole - Solder |
| Mechanical Attachment | |
| Mating Retention | With |
| Mating Retention Type | Detent Window |
| Mating Alignment | With |
| Mating Alignment Type | Polarization |
| PCB Mount Retention | Without |
| PCB Mount Alignment | Without |
| Connector Mounting Type | Board Mount |
| Housing Features | |
| Centerline (Pitch) | 2.54 mm[.1 in] |
| Housing Material | Thermoplastic |
| Dimensions | |
| Row-to-Row Spacing | 2.54 mm[.1 in] |
| PCB Thickness (Recommended) | 1.4 mm[.055 in] |
| Usage Conditions | |
| Housing Temperature Rating | Standard |
| | |



| Operating Temperature Range | -65 – 105 °C[-85 – 221 °F] |
|-----------------------------|----------------------------|
| Operation/Application | |
| Solder Process Feature | Board Standoff |
| Circuit Application | Signal |
| Industry Standards | |
| Agency/Standard | CSA |
| Approved Standards | CSA LR7189, UL E28476 |
| UL Flammability Rating | UL 94V-0 |
| | |

40

Tray

Product Compliance

Packaging Features

Packaging Type

Packaging Quantity

For compliance documentation, visit the product page on TE.com>

| EU RoHS Directive 2011/65/EU | Compliant |
|---|---|
| EU ELV Directive 2000/53/EC | Compliant |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235) Does not contain REACH SVHC |
| Halogen Content | BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources. |
| Solder Process Capability | Wave solder capable to 240°C |

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



Compatible Parts



Also in the Series | AMPMODU Headers



PCB Connector Mounting(1)



PCB Connector Shrouds(1)



PCB Headers & Receptacles(4872)



PCB Latches, Locks & Retainers(1)



Wire-to-Board Connector Assemblies & Housings(5)



Wire-to-Board Connector Contacts(65)

Customers Also Bought



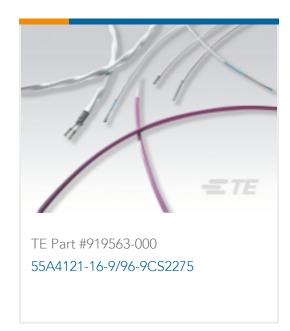
















Documents

Product Drawings

40 MODII HDR DRRA SHRD LF

English

CAD Files

3D PDF

English

Customer View Model

ENG_CVM_6-103166-8_K.2d_dxf.zip

English

Customer View Model

ENG_CVM_6-103166-8_K.3d_igs.zip

English

Customer View Model

ENG_CVM_6-103166-8_K.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Datasheets & Catalog Pages

AMPMODU_INTERCONNECTION_SYSTEM_SECTION5

English

Product Environmental Compliance

TE Material Declaration

English